



Device  
Package  
REF DOC

VS8053B  
48L LQFP 7x7x1.4 mm  
ait\_bond\_VS8053B-L-RoHS\_rev\_B.xls

Document: A  
Rev: 2.0  
Marking on device:

VS8053B  
PPPPPPPPPP  
YYWW

where, P P P P P P P P P P = Lot ID  
Y Y W W = assembly Year and Week > 0935

no	Part Name	Material Name	Component WT (mg)	Material Content (Element)	CAS#	Element Wt (%)	Element WT (mg)	WT% of total unit Wt	ppm
1	Die	Silicon Chip (159x160x10 mils)	9.947	Silicon	7440-21-3	100.00	9.947	5.486	54858.511
2	Lead Frame	Spot Ag Copper (Olin C7025)	79.408	Copper	7440-50-8	96.200	74.834	41.272	412715.460
				Ni	7440-02-0	3.000	2.334	1.287	12870.545
				Si	7440-21-3	0.650	0.506	0.279	2788.618
				Mg	7439-95-4	0.150	0.117	0.064	643.527
				Silver	7440-22-4		1.618	0.892	8923.401
3	Mold Compound	G700LX	86.394	Silica Fused	60676-86-0	81.500	70.411	38.832	388322.974
				Epoxy Resin	Trade Secret	10.000	8.639	4.765	47646.991
				Phenol Resin	Trade Secret	8.000	6.912	3.812	38117.593
				Carbon Black	1333-86-4	0.500	0.432	0.238	2382.350
4	Gold Wire	Gold (1.0 mils)	1.170	Au	7440-57-5	99.990	1.170	0.645	6451.999
				Dopant	-	0.010	0.000	0.000	0.645
5	Die Attach Material	CRM 1076 NS	1.502	Silver (Ag)	7440-22-4	82.000	1.232	0.679	6792.594
				Epoxy resin	9003-36-5	10.000	0.150	0.083	828.365
				Diluent	Trade Secret	2.000	0.030	0.017	165.673
				Dicyandiamide	461-58-5	0.900	0.014	0.007	74.553
				Hardener	Trade Secret	5.100	0.077	0.042	422.466
6	Solder	Sn 100	2.900	Sn	7440-31-5	99.987	2.900	1.599	15991.656
				Pb	7439-92-1	0.005	0.000	0.000	0.800
				Cu	7440-50-8	0.003	0.000	0.000	0.480
				Cd	7440-43-9	0.001	0.000	0.000	0.160
				Bi	7440-69-9	0.003	0.000	0.000	0.480
				Sb	7440-36-0	0.001	0.000	0.000	0.160
Total Unit Weight =			181.321						